Construction General examination Visually and by measuring instrument. Marking Confirmed visually. Electric characteristics Contact Resistance millivoit level method Inautation resistance millivoit level method Inautation resistance millivoit level method Inautation resistance Mechanical Characteristics Wechanical Operation 500 V AC for 1 min. No flashover or breakdown. Mechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. Wechanical operation 500 W AC for 1 min. No flashover or breakdown. We be electrical discontinuity of 1 µs. 2No damage, crack or looseness of parts. 2No damage, crack or looseness of parts. 3No deformation resistance: 20mu MAX 2 Inautation aloose a second parts. 3No deformation of case of excessive	Applicable	e standard										
Humidity range	Operating Temperature ra		ange	-40 °C to +105°C (Note1) Tem		Tem	•			-10 °C to +60°C (Note3)		
Applicable contact DFS-2428SCR/S OVACTO Current 22 AWG : 35 A 28 AWG : 25 A 28 AWG : 26 AWG :	Rating	Humidity range				midity range			40% to 70% (N	lote3)		
Appointment Option Solve						UI (C-UI	Voltage		AC 50 V		
Current 24 AWG : 25 A 28 AWG : 22 A 28 AWG : 24 A 28 AWG : 24 A 28 AWG : 25 A 28 AWG : 24 A 28 AWG : 25 AWG : 28 AWG : 25 AWG : 28 AWG : 25 AWG : 28 AWG :				,	*)							
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Insulation resistance 100 V DC. 100 MD MIN. X			20mV MAX, 1mA(DC or 1000Hz).				10mΩ MAX.				X	_
Voltage proof S00 V AC for 1 min. No flashover or breakdown. X Mechanical characteristics			100 V DC			100 MO MIN.				X	+-	
Mechanical characteristics Solimes insertion and extraction. ①Contact resistance: 20mΩ MAX. 2.No damage, crack or looseness of parts. X											-	
Mechanical operation So times insertion and extraction. ①Contact resistance: 20mΩ MAX X 2 2 2 2 2 3 3 3 2 3 3							1		Jul			1
Vibration Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 10 cycles for 3 direction. 2/No electrical discontinuity of 1 μs. 3/No electrical disc				insertion and extraction.			(1)Con	tact resist	tance	: 20mΩ MAX	X	Τ_
0.75 mm, at 10 cycles for 3 direction. 2 No damage, crack or looseness of parts. 3	Medianical operation		50 times insertion and extraction.				©					
Shock 490 m/s duration of pulse 11 ms at 3 times each for 3 both axial directions. X	Vibration						-	-				_
Sobt axial directions. Summer to the content of the summer to the su	Chook 40		0.75 mm	0.75 mm, at 10 cycles for 3 direction.				②No damage, crack or looseness of parts.			V	
Damp heat (Steady State)	Snock										^	_
Cate and procession Cate	Environme	ental charac	cteristics								<u> </u>	
Rapid change of temperature -55°C → +105°C Time 30min → 30min ∪ 1 more 5 cycles. (The transferring time of the tank is 2 - 3 min) (After leaving the room temperature for 1 - 2h.) Resistance to soldering heat 1 Reflow soldering «Reflow time» Number of reflow cycles: 2 cycles max. Duration above 220°C, 60sec. max. Peak temperature: 250°C 10 sec. max. Peak temperature: 250°C 10 sec. max. Pre-heat time (min): 150°C Pre-heat time (min): 90 sec. Pre-he											X	_
Time 30min → 30min Under 5 cycles. Time 30min → 30min Under 5 cycles. Time 30min → 30min Under 5 cycles. The transferring time of the tank is 2 - 3 min) (After leaving the room temperature for 1 - 2h.) Resistance to soldering heat I) Reflow soldering Selfow soldering with me Number of reflow cycles: 2 cycles max. Duration above 220°C, 60sec. max. Peak temperature: 250°C 10 sec. max. Pre-heat time Pre-heat time (min): 150°C Pre-heat time (max): 120 sec. 2) Manual soldering Soldering inner temperature: 350±10°C, Soldering time: 3s No strength on contact. Soldered at solder temperature, 245°C for in immersion, duration, 5s. Soldered at solder temperature, 245°C for in immersion, duration, 5s. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range are applied for interim storage during transportation. Count Description of revisions Designed Checked Date Count Description of revisions Designed Is. KUMAZAWIA 20180426 Remarks Approved His. OkAWIA 20180426 Unless otherwise specified, refer to IEC 60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing No. ELC-354319-78-01 Part No. DF65-7P-1. 7V (78)							_					
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Checked Count Description of revisions Checked Date	temperature		_									
After leaving the room temperature for 1 - 2h.) Resistance to soldering 1) Reflow soldering (Reflow time) Reflow time) No deformation of case of excessive Number of reflow cycles: 2 cycles max. Duration above 220°C, 60sec. max. Peak temperature: 250°C 10 sec. max. Peak temperature: 250°C 10 sec. max. Pre-heat time) Pre-heat time) Pre-heat time Pre-heat					? - 3 min)							
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